

Semiconductor Equipment Corporation

For almost 30 years Semiconductor Equipment Corporation has set the standard for high quality dicing tape.

Tapes are selected for your application based on die size and blade thickness. Small die and hard to cut materials require higher tackiness, while larger die call for lower tackiness. Thicker blades require thicker tape.

For additional information, please contact our Tape Specialist at (805) 529-2293 or sales@semicorp.com.

SWT (Semiconductor Wafer Tape) Most Popular



SEC's economical electronic grade dicing tape.

This product consist of PVC film coated with a pressure sensitive acrylic-based adhesive manufactured in clean room environment. For easy unwind, the backing of the PVC-film is coated with a silicone release. The product is wound on a plastic core.



Blue Low Tack Rolls P/N 18733
Blue Medium Tack Rolls P/N 18074
(Thickness 75 um / .003"
Length 200 M / 660'



Thick Clear Low Rolls P/N 24353
Thick Clear Medium Rolls P/N 24374
Thickness 120 um / .0047"
Length 100 M / 330'



Clear Low Tack Rolls P/N 19161
(Thickness 100 um / .004"
Length 100 M & 200 M / 330' & 660'

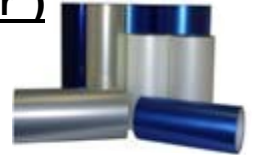


Squares

Blue Low and Medium tapes are available in precut squares mounted on release paper. Standard sizes are 5.75" and 7.50". Custom sizes are also available.

High Purity Pressure Sensitive Tape with Liner (Nitto "Elep Holder")

Low ionic impurities and adhesion stability make this the perfect tape for your clean room application. **Excellent expandability.**



UV Curable Dicing Tape with Liner (Nitto "Elep Holder")

A very high adhesive strength secures wafers firmly during dicing, while allowing for easy removal after exposure. UV tape is an excellent fit for small-die application and non-standard substrate such as FR4 board BGA wafers



UV Tape for Silicon Die P/N 24339 (DU-300) *Our most popular UV tape*

Polyolefin, 85 um thick, Thin adhesive (5um) Low chipping, Low adhesive contamination, Expandable

UV Tape for Difficult Cut Substrates P/N 24351 (NBD-5170K) *For dicing BGA & ceramic*

Polyolefin, 170 um thick, Thick adhesive (20um)

UV Tape for Back Metallization P/N 25551 (DU-2187G) 88um thick

Heat Release Tape (Nitto "Revalpha")

The thermal release tape, REVALPHA is a unique adhesive tape. Adhesion equivalent to a normal adhesive tape at room temperatures, and can be easily peeled off when required, simply by heating. Heat used for removal can be selected (90°C, 120°C, 150°C, 170°C) As tape removal is guaranteed at a uniform temperature, higher levels of labor-saving automation can be achieved. No damage to substrate when removing tape.



Backgrinding Tape (Nitto "Elep Holder")



Low contamination, consistent thickness accuracy, high acid resistance and effective protection during wet processes.

UV Backgrinding tape for BGA P/N 25940 (UB-3102D) 100um thick

High Tack Backgrinding Tape P/N 25800 (BT-315) 85 um thick

Anti-ESD Backgrinding Tape P/N 25826 (BT315s) 85 um thick

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5154 Goldman Avenue Moorpark, CA 93021

Phone: 805-529-2293 Fax: 805-529-2193 www.semicorp.com sales@semicorp.com